World Literature Review

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FAX Numbers (when calling from U.S.)	
GALVANO	**011-33-01-30-45-90-50**
Galvanotechnik	**011-49-75 81-1756**
Hyomen Gijutsu	**011-81-3-3252-3288**
Metalloberfläche	**011-49-75 81-1756**
SURFACES	**011-33-01-43-47-30-80**
Trans. of the IMF	**011-44-0121-666-6316**

Review Covers Recent Issues of Hyomen Gijutsu & Transactions of the IMF

Hyomen Gijutsu

December 1998 • Vol. 49, No. 12

Plating & Alternative Processes

“Bump Process Technology for LSI Wafer,” S. Honma, J. Yoshioka & Y. Hiruta

“Plating Technologies Adaptable to Lead-free Soldering,” H. Nawafune

“Production of Compound Eyes Metal Molds by Bright Plating Method,” M. Kawasaki, T. Asanuma & T. Suzuki

“Influence of Nickel Plating Underlayer Deposition Conditions on Bending Characteristics of Palladium Plating Leadframe,” A. Chinda, H. Akino & T. Yonekawa

“Influence of Electroless Gold Plating on Wire Bondability & Ball Solderability on Tape Substrate for BGA Packages,” A. Chinda, N. Miyamoto & O. Yoshioka

“A Very Stable Non-cyanide Electroless Gold Plating Bath Using Thiourea & Hydroquinone as a Cooperating Double-reductant System,” T. Inoue, S. Ando, J. Ushio, H. Okudaira, H. Takehara, T. Ota, H. Yamamoto & H. Yokono

“Laser-enhanced Electroless Gold Plating on Polyimide Resin Film,” S. Nagamine, K. Kobayakawa & Y. Sato

“Investigation for Alkaline Electroplating Bath of Sn-Ag Alloy Using 5,5-Dimethylhydantion,” T. Ise, M. Yuasa, I. Sekine & Y. Shindou

“Anode Behavior in Sn-Ag Alloy Plating from Ammonium Citrate-Potassium Iodide Baths,” Y. Fujiwara, T. Narahara, H. Enomoto, K. Funada & T. Omi

“Electroless Palladium Plating from Monoaminodicarboxylic Acid Complex Bath Using Formic Acid as a Reducing Agent,” H. Nawafune, S. Nakao, S. Mizumoto, E. Uchida & T. Okada
“Adhesion Improvement Between Conductor & Insulation Layer with Electroless Copper Plating Using Hypophosphite as a Reducing Agent,” T. Mizuguchi, T. Kobayashi, T. Fujinami & H. Honma

Printed Circuit Board Technology
“New Plating Technologies for Semiconductor Packaging & Interconnect Technology,” S. Wakabayashi
“EMI Shielding by Electroless Plating,” K. Nakamura
“Circuit Technology for 3-D Packaging—Plating Technologies for MID,” R. Komagine
“Technology of Electrodeposited Copper Foil,” N. Takahashi
“Via Filling by Electroplating Under Various Waveforms,” T. Kobayashi, J. Kawasaki, J. Ishibashi, K. Tanaka & H. Honma
“Effect of Complexing Agents on Micro-pattern Formation Using Electroless NiB Plating,” T. Yokoshima, H. Yuasa, M. Kim & T. Osaka
“Fabrication of Amorphous Fe-B Electrodeposited Films for Micromagnetic Devices,” N. Fujita, P.B. Lim, M. Izaki, M. Inoue, K. Arai & T. Fujii
“Characterization of Electrodeposited Magnetic Nanostructures,” Y. Jyoko, S. Kashiwabara & Y. Hayashi

Transactions of the Institute of Metal Finishing (IMF)

November 1998 • Vol. 76, Part 6

Plating & Alternative Processes
“Electrodeposition from Trivalent Chromium Electrolytes,” T. Pearson & E. Long
“The Mechanism of Crack Formation in Plasma-sprayed Enamel,” Y. Bao, T. Zhang & D.T. Gawne
“Anodic Behavior of Electrodeposited Zn-Sn Alloys,” V. Ivanova, G. Raichevski, V. Krastev & S. Vitkova
‘Electron Microscopic Investigations on the Morphology & Crystal Growth Characteristics of Black Nickel Thin Films,” M.V. Ananth
“The Use of Phosphates in ‘P’ Salt Electroplating Solutions for Platinum,” S.E. Hadian & D.R. Gabe
“Ellipsometric Study of Passive Films on the Stainless Steel SS304,” S.V. Phadnis, M.K. Totlani & D. Bhattacharya
“A Study on the Effect of Bath Composition on the Internal Stress of a Palladium Electrodeposit,” F-Z. Yang, S-K. Xu, L. Huang, X-Y. Zhang & S-M. Zhou
“Development of Electrolessly Deposited Nano Fe-P Films,” H. Matsuda, S. Yae, I. Iwagishi & H. Matsuo

Cleaning & Pretreatment
“Pretreatments to Improve the Bondability of Hot-dipped Galvanized Mild Steel,” G.W. Critchlow, K.H. Bedwell & M.E. Chamberlain
“Preparation & Electrical Resistance Characteristics of Electroless Copper-Nickel Alloy Deposits,” H. Nawafune, T. Uegahi, S. Mizumoto, M. Ishikawa & T. Nakamura

Environmental Concerns
“Preventing Environmental Contamination by Non-ionic Surfactants & Nickel,” J.J. Snukiskis, D.V. Kauspediene & A.J. Gefeniene

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